



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



GHS100A120S2B1

Si IGBT hybrid module with SiC SBDs



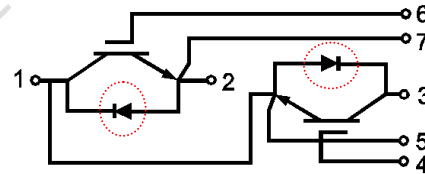
Features:

- Low Saturation Voltage: $V_{CE(sat)} = 1.90V @ I_C = 100A, T_C=25^\circ C$
- Low Switching Loss
- SiC SBD for Freewheeling diode: $V_F = 1.60V @ I_F = 100A, T_J=25^\circ C$
- 100% RBSOA Tested ($2 \times I_C$)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement
- UL E 338085



Applications:

- Welding Machine/ Cutting Machine
- Induction Heating
- Ultrasonic Device
- PV System
- SMPS



Maximum Rated Values of IGBT ($T_C=25^\circ C$ unless otherwise specified)

V_{CES}	Collector-Emitter Blocking Voltage		1200	V
V_{GES}	Gate-Emitter Voltage		± 20	V
I_C	Continuous Collector Current	$T_C = 80^\circ C$	100	A
		$T_C = 25^\circ C$	200	A
I_{CM}	Repetitive Peak Collector Current	$T_J = 175^\circ C$	200	A
t_{SC}	Short Circuit Withstand Time		>10	μs
P_D	Maximum Power Dissipation per IGBT	$T_C = 25^\circ C$ $T_{Jmax}=175^\circ C$	500	W

Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static characteristics

Symbol	Description	Conditions	Min	Typ	Max	Unit
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C = 1\text{mA}, V_{CE} = V_{GE}$	3.5	4.0	5.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C = 100\text{A}, V_{GE} = 15\text{V}$	$T_J = 25^\circ\text{C}$	1.90	2.10	V
			$T_J = 125^\circ\text{C}$	2.20	2.40	V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE} = 0\text{V}, V_{CE} = V_{CES}, T_J = 25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20\text{V}, V_{CE} = 0\text{V}, T_J = 25^\circ\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$		10.0		nF
C_{oes}	Output Capacitance			0.54		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC} = 600\text{V}, I_C = 100\text{A}, R_G = 33\ \Omega, V_{GE} = \pm 15\text{V},$ Inductive Load	$T_J = 25^\circ\text{C}$		250		ns
			$T_J = 125^\circ\text{C}$		250		
t_r	Rise Time		$T_J = 25^\circ\text{C}$		125		ns
			$T_J = 125^\circ\text{C}$		125		
$t_{d(off)}$	Turn-off Delay Time		$T_J = 25^\circ\text{C}$		600		ns
			$T_J = 125^\circ\text{C}$		625		
t_f	Fall Time		$T_J = 25^\circ\text{C}$		165		ns
			$T_J = 125^\circ\text{C}$		185		
E_{on}	Turn-on Switching Loss		$T_J = 25^\circ\text{C}$		TBD	15.5	mJ
			$T_J = 125^\circ\text{C}$		TBD	16.0	
E_{off}	Turn-off Switching Loss	$T_J = 25^\circ\text{C}$		TBD	3.8	mJ	
		$T_J = 125^\circ\text{C}$		TBD	6.1		
Q_g	Total Gate Charge	$T_J = 25^\circ\text{C}$		685		nC	
RBSOA	Reverse Bias Safe Operation Area	$I_C=200\text{A}, V_{CC}=960\text{V}, V_p=1200\text{V}, R_g = 33\ \Omega, V_{GE}=\pm 15\text{V to } 0\text{V}, T_J = 150^\circ\text{C}$	Trapezoid				
SCSOA	Short Circuit Safe Operation Area	$V_{CC} = 300\text{V}, V_{GE} = 15\text{V}, T_J = 150^\circ\text{C}$	10			μs	
$R_{\theta JC}$	IGBT Thermal Resistance: Junction-To-Case			0.30		$^\circ\text{C/W}$	

Maximum Rated Values of SiC Diode ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Description	Conditions	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	$T_J=25^\circ\text{C}$	1200	V
I_F	Diode Continuous Forward Current	$T_C=125^\circ\text{C}$, $T_J=175^\circ\text{C}$	162	A
$I_{F,SM}$	Surge Non-repetitive Forward Current	$T_C=125^\circ\text{C}$, $t_p=8.3$ ms sine half wave	500	A
dv/dt	Diode dv/dt Ruggedness	Turn-on slew rate, repetitive	50	V/ns

Electrical Characteristics of Diode ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Description	Conditions	Min	Typ	Max	Unit
V_R	DC Blocking Voltage	$I_R=100$ uA	1200			V
V_F	Forward Voltage	$I_F = 100\text{A}$, $V_{GE} = 0\text{V}$	$T_J = 25^\circ\text{C}$	1.6	1.8	V
			$T_J = 175^\circ\text{C}$	2.2	2.7	
I_R	Reverse leakage Current	$V_R=1200\text{V}$	$T_J = 25^\circ\text{C}$	16	500	μA
		$V_R=1200\text{V}$	$T_J = 175^\circ\text{C}$	580		
Q_C	Total Capacitive Charge	$V_R=1200\text{V}$		431		nC
C	Total Capacitance	$V_R=1\text{V}$, $f=1$ MHz		6349		pF
		$V_R=600\text{V}$, $f=1$ MHz		370		
		$V_R=1200\text{V}$, $f=1$ MHz		359		
$R_{\theta JC}$	Diode Thermal Resistance: Junction-To-Case			TBD	0.31	$^\circ\text{C/W}$

Module

Symbol	Description	Min	Typ	Max	Unit
V_{iso}	Isolation Voltage(All Terminals Shorted)			2500	V
T_J	Maximum Junction Temperature			175	$^\circ\text{C}$
T_{JOP}	Maximum Operating Junction Temperature Range	-40		+150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-40		+125	$^\circ\text{C}$
$R_{\theta CS}$	Case-To-Sink (Conductive Grease Applied)		0.1		$^\circ\text{C/W}$
T	Power Terminals Screw:M5	3.0		5.0	N·m
T	Mounting Screw:M6	4.0		6.0	N·m
G	Weight		180		g

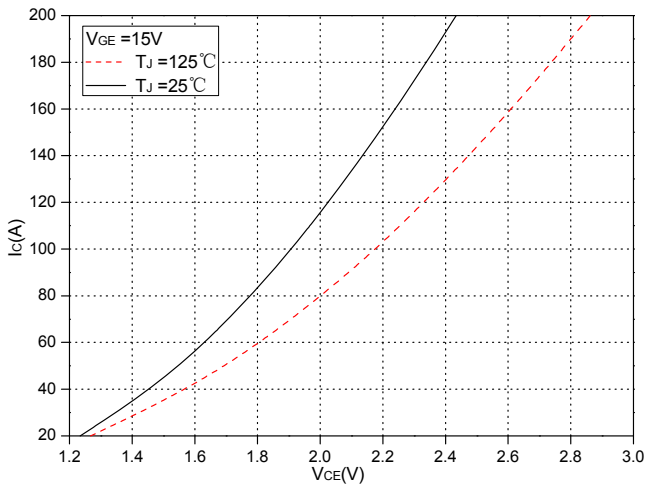


Fig.1 Typical Saturation Voltage Characteristics

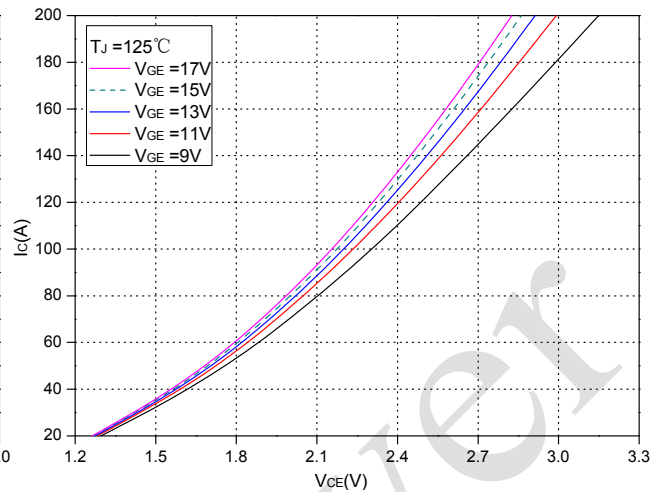


Fig.2 Typical Output Characteristics

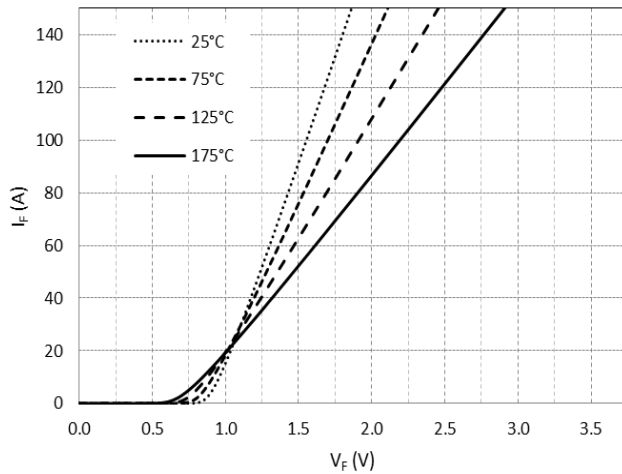


Fig.3 Forward Characteristics of Diode

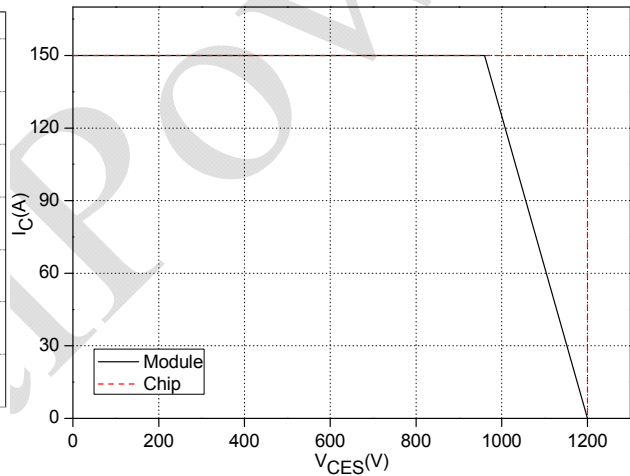


Fig.4 Reverse Bias Safe Operation Area (RBSOA)

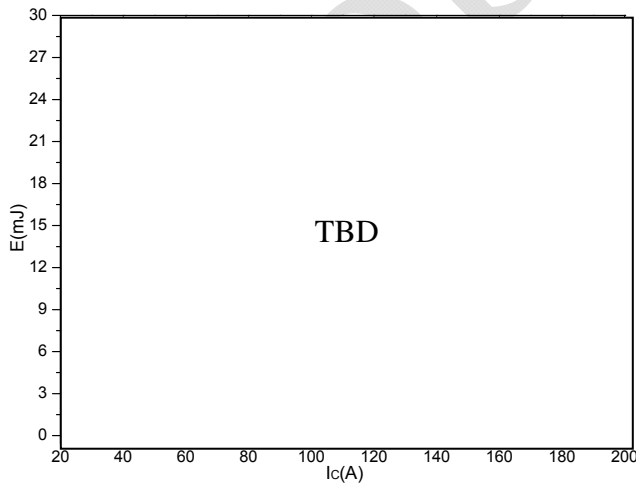


Fig.5 Typical Switching Loss vs. Collector Current

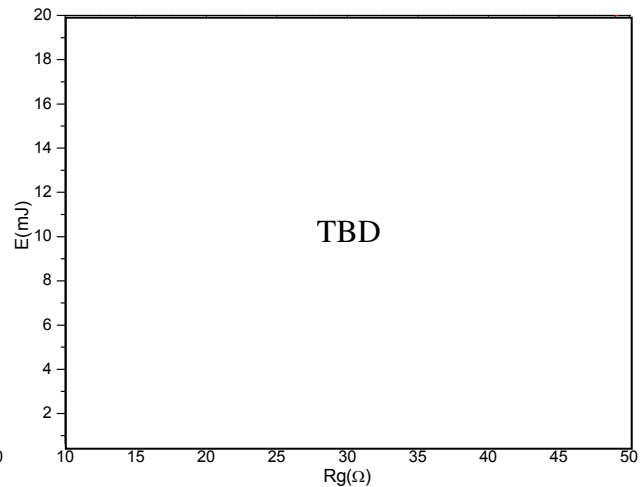


Fig.6 Typical Switching Loss vs. Gate Resistance

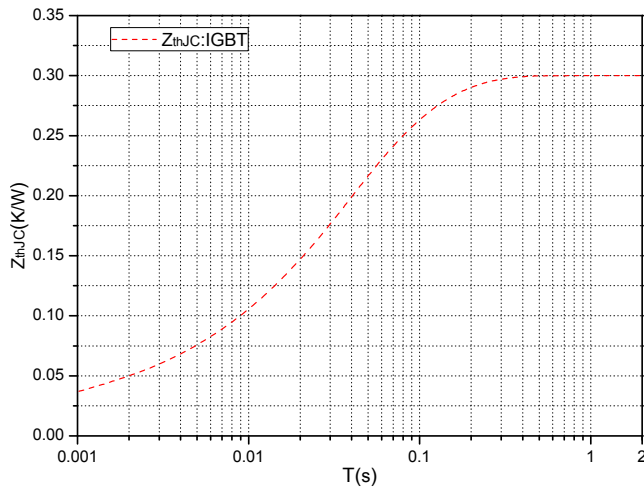


Fig.7 Transient thermal impedance (IGBT)

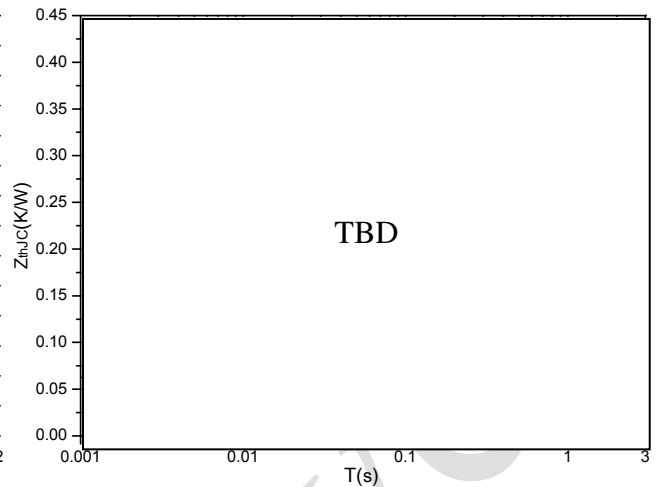


Fig.8 Transient thermal impedance (SiC Diode)

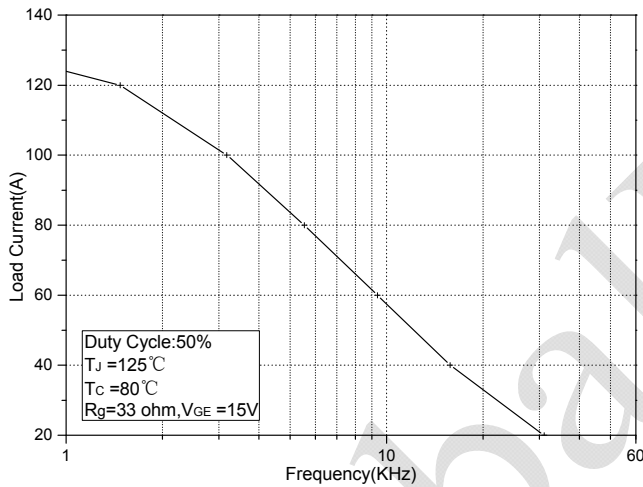


Fig.9 Typical Load Current vs. Frequency

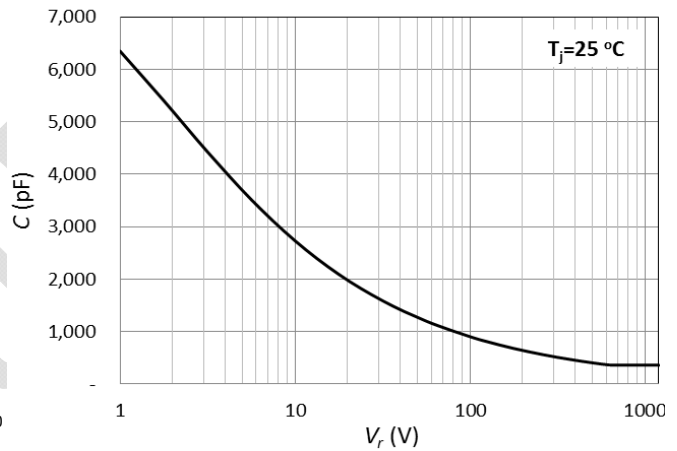


Fig.10 Capacitance Characteristics of Diode

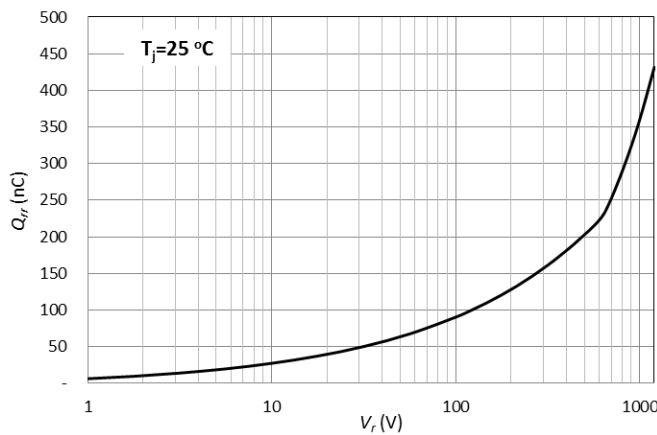


Fig. 11 Diode Recovery Charge

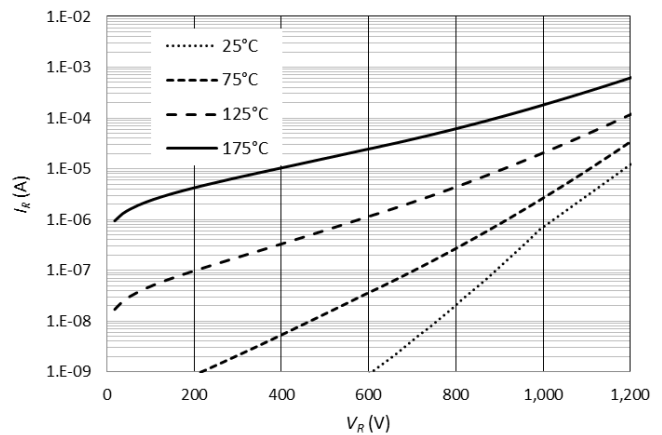
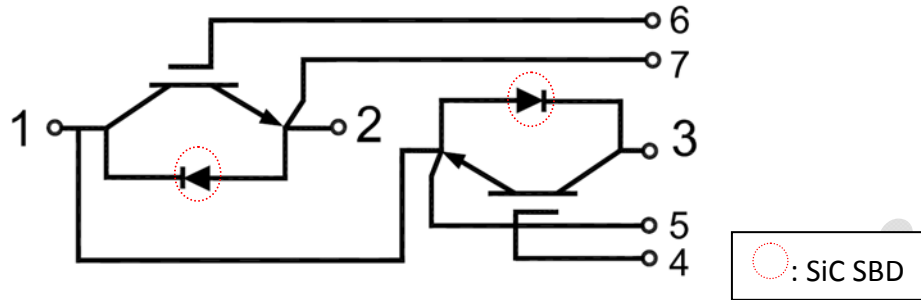
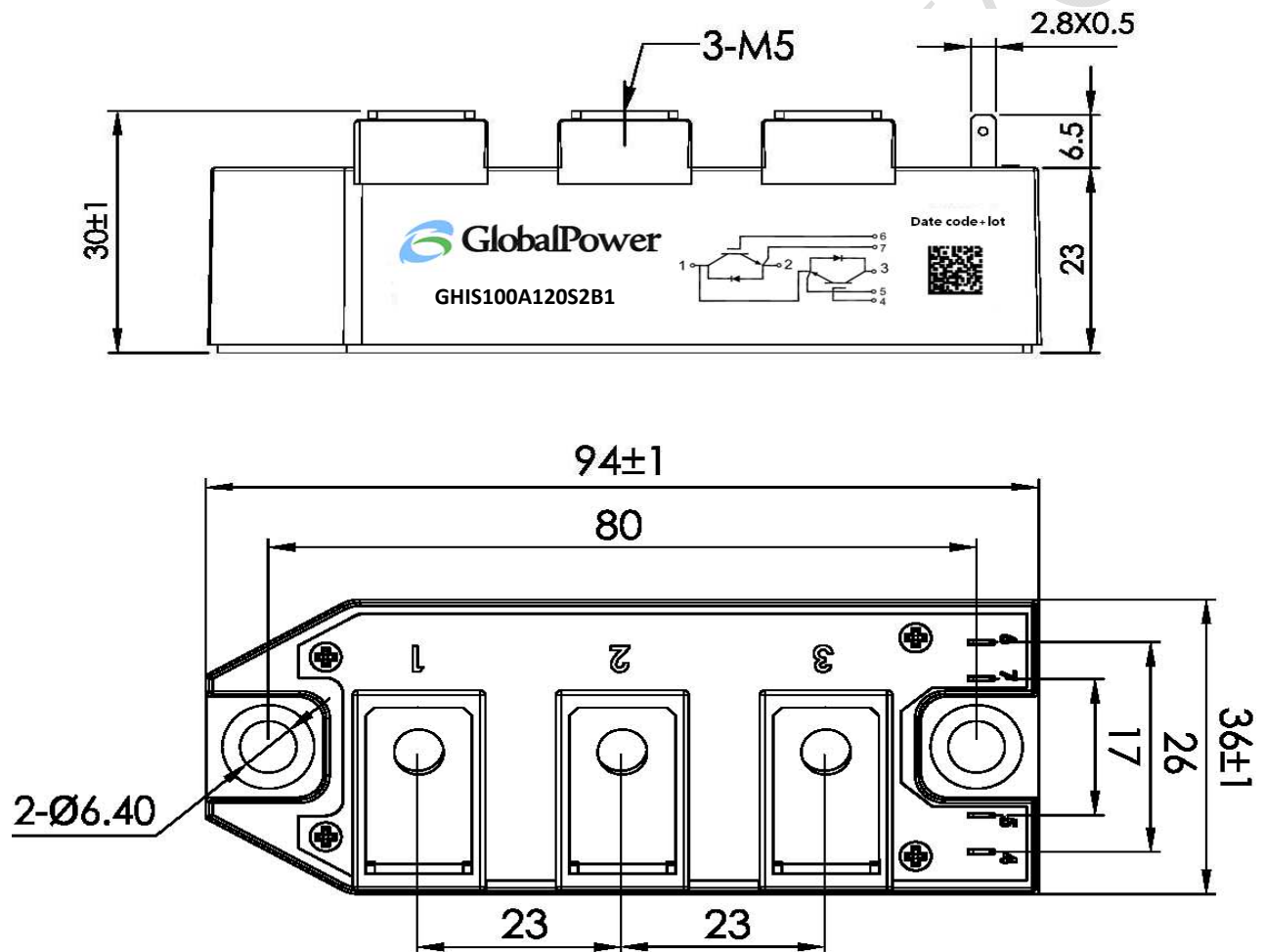


Fig. 12 Diode Leakage Current (Parameterized on Tj)

Internal Circuit:



Package Outline (Unit: mm):



Revision History

Date	Revision	Notes
4/22/2015	0.1	Initial release of preliminary datasheet

Global Power Technologies Group

20692 Prism Place
 Lake Forest, CA 92630
 TEL (949) 207-7500
 FAX (949) 613-7600
 E-mail: info@gptechgroup.com
 Web site: www.gptechgroup.com



Notes

- RoHS Compliance**
 The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented March, 2013. RoHS Declarations for this product can be obtained from the Product Documentation sections of www.gptechgroup.com.
- REACH Compliance**
 REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact our office at GPTG Headquarters in Lake Forest, California to insure you get the most up-to-date REACH SVHC Declaration.
 REACH banned substance information (REACH Article 67) is also available upon request.
- This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control.
- To obtain additional technical information or to place an order for this product, please contact us. The information in this datasheet is provided by Global Power Technologies Group. GPTG reserves the right to make changes, corrections, modifications, and improvements of datasheet without notice.